

# WEST Search History

6715963

DATE: Wednesday, June 05, 2002

**Set Name Query**  
side by side

**Hit Count**      **Set  
Name**  
result set

DB =PGPB,JPAB,EPAB,DWPI,TDBD; PLUR =YES; OP = ADJ

L7	((urethane or polyurethane) near5 (epoxy or epoxide)) and (((underfill\$4 or sealant or encapsula??\$2 or adhesive) near10 ((urethane or polyurethane) near5 (epoxy or epoxide) )) and ((carbon adj (black or fiber or fibre)) or graphite or ((nickel or copper or aluminum or palladium or silver or gold or platinum or Ni or Cu or Al or Ag or Au or Pt or Pd) near5 (powder or particle or filler)) )) and (underfill\$4 or sealant or encapsula??\$2 or adhesive)	107	L7
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DB=USPT; PLUR = YES; OP = ADJ

L6	14 and ( (523/\$.ccls.) or (525/\$.ccls.) )	90	L6
L5	14 and ( (523/\$.ccls.) or (525/\$.ccls.) )	90	L5
L4	12 and 13	667	L4
L3	(carbon adj (black or fiber or fibre)) or graphite or ((nickel or copper or aluminum or palladium or silver or gold or platinum or Ni or Cu or Al or Ag or Au or Pt or Pd) near5 (powder or particle or filler))	171200	L3
L2	(underfill\$4 or sealant or encapsula??\$2 or adhesive) near10 11	2151	L2
L1	(urethane or polyurethane) near5 (epoxy or epoxide)	19094	L1

END OF SEARCH HISTORY

**WEST**

Generate Collection

Print

JP 60-206882

L7: Entry 91 of 107

File: DWPI

Oct 18, 1985

DERWENT-ACC-NO: 1985-299693

DERWENT-WEEK: 198548

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TITLE: Heat-curable epoxy resin adhesive - comprising glycidyl ether epoxy resin, modified epoxy prepd. from urethane prepolymer and epoxy resin, and potential hardening agent

PATENT-ASSIGNEE:

ASSIGNEE

CODE

SUNSTAR GIKEN KK

SUNZ

PRIORITY-DATA: 1984JP-0063763 (March 30, 1984)

PATENT-FAMILY:

PUB-NO

PUB-DATE

LANGUAGE

PAGES

MAIN-IPC

JP 60206882 A

October 18, 1985

004

INT-CL (IPC): C08G 59/20; C09J 3/16

ABSTRACTED-PUB-NO: JP60206882A

BASIC-ABSTRACT:

Adhesive of single liq. type for automobiles comprises essentially (A) epoxy resin of glycidyl ether type, (B) modified epoxy resin prepd. by reacting (B1) urethane prepolymer prepd. by reacting polytetramethylene ether glycol and diisocyanate and contg. terminal isocyanate gp. and (B2) epoxy resin contg. at least one OH gp. and (C) potential hardening agent.

Pref. (A) is diglycidyl ether of 2,2-bis(4-hydroxyphenyl) propane (bisphenol-A) prepd. from polyhydric phenol and epichlorohydrin, diglycidyl ether of adduct of bisphenol A with ethylene oxide, reaction prod. of aliphatic polyol and epichlorohydrin (e.g. triglycidyl ether of glycerin or diglycidyl ether of 1,6-hexane diol) or hydrogenated prod. of polyhydric alcohol or adduct with alkylene oxide and epichlorohydrin. (A) is liq. at room temp. and has pref. epoxy equiv. of up to 500. (B1) is prepd. by reacting polytetramethylene ether glycol having mol. wt. of 500-5,000 with diisocyanate (equiv. ratio of NCO/OH of 1.2-3) at 60-120 deg.C for 1-6 hr. (B2) is prepd. by reacting epoxy resin contg. at least one OH gp. (e.g. glycidyl ether of bisphenol A or aliphatic polyol) (equiv. ratio of NCO/OH of at least 1) at 80-100 deg.C. (C) is pref. dicyanodiamide, 4,4'-diaminodiphenylsulphone, 2-n-heptane decylimidazole, isophthalic acid dihydrazide, N,N-dialkyl urea, N,N-dialkylthiourea or melamine deriv.) and blended in amt. 1-30 wt.pts. per 100 pts. of (A). Adhesive compsn. may be added with filler (e.g. CaCO<sub>3</sub>, clay, SiO<sub>2</sub>, talc, carbon black or metal powder), anticorrosive pigment (e.g. phosphate or Zn chromate), plasticiser and/or solvent.

ADVANTAGE: - Adhesive compsn. is usable for bonding steel plates for painting electrodepositing paint.

CHOSEN-DRAWING: Dwg 0/0

TITLE-TERMS: HEAT CURE POLYEPOXIDE RESIN ADHESIVE COMPRISE GLYCIDYL ETHER POLYEPOXIDE RESIN MODIFIED EPOXY PREPARATION URETHANE PREPOLYMER EPOXY RESIN POTENTIAL HARDEN AGENT

DERWENT-CLASS: A21 A25 A81 G03

WEST

Generate Collection

Print

JP 60-235877

L7: Entry 90 of 107

File: DWPI

Nov 22, 1985

DERWENT-ACC-NO: 1986-011136  
DERWENT-WEEK: 198602  
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TITLE: Epoxy! resin adhesive for automobiles - comprises glycidyl ether epoxy! resin, urethane!-modified epoxy! resin, curing agent and electrically conductive material

PATENT-ASSIGNEE:  
ASSIGNEE  
SUNSTAR GIKEN KK

CODE  
SUNZ

PRIORITY-DATA: 1984JP-0092167 (May 8, 1984)

## PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE	PAGES	MAIN-IPC
JP 60235877 A	November 22, 1985		005	
JP 91049692 B	July 30, 1991		000	

## APPLICATION-DATA:

PUB-NO	APPL-DATE	APPL-NO	DESCRIPTOR
JP60235877A	May 8, 1984	1984JP-0092167	
JP91049692B	May 8, 1984	1984JP-0092167	

INT-CL (IPC): B23P 11/00; B62D 65/00; C09J 3/16; C09J 163/02

ABSTRACTED-PUB-NO: JP60235877A  
BASIC-ABSTRACT:

Adhesive is obtd. by mixing a one-pack heat-uncurable epoxy resin adhesive consisting of (a) glycidyl ether type epoxy resin, (b) modified epoxy resin formed by reacting urethane prepolymer contg. terminal isocyanate gp. with epoxy resin having at least one hydroxy gp. per molecule and (c) latent curing agent, with (d) electrically conductive material.

Ratio of (a), (b), (c) and (d) is 100:20-200:1-30:2-200. (d) consists of carbon powder and/or graphite powder. To the adhesive is opt. added a rust-proofing agent. The urethane prepolymer contg. terminal isocyanate gp. is obtd. by reacting polytetramethylene ether glycol with diisocyanate, in the ratio 1.2-3 equivs. isocyanate gp. per hydroxy gp. at 60-120 deg.C (c) is dicyandiamide 4,4'-diaminodiphenyl sulphone imidazole deriv., isophthalic dihydrazide and N,N'-dialkyl urea deriv.

USE - The adhesive is pref. used for adhesion of coated steel plate to be electrically coated.

CHOSEN-DRAWING: Dwg.0/0

TITLE-TERMS: POLYEPOXIDE RESIN ADHESIVE AUTOMOBILE COMPRISE GLYCIDYL ETHER POLYEPOXIDE RESIN POLYURETHANE MODIFIED POLYEPOXIDE RESIN CURE AGENT ELECTRIC CONDUCTING MATERIAL

DERWENT-CLASS: A21 A81 G03 P56 Q22

WEST

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Print

JP 43-17052

L7: Entry 105 of 107

File: DWPI

Sep 13, 1974

DERWENT-ACC-NO: 1975-44920W  
DERWENT-WEEK: 197527  
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TITLE: Steel bonding compn - conta polyurethane epoxy blend adhesive

PATENT-ASSIGNEE:

ASSIGNEE

SEKISUI CHEMICAL KK

CODE

SEKI

PRIORITY-DATA 1972JP-0129154 (December 21, 1972)

PATENT-FAMILY:

PUB-NO

PUB-DATE

LANGUAGE

PAGES

MAIN-IPC

JP 49097052 A

September 13, 1974

000

JP 76025251 B

July 29, 1976

000

INT-CL (IPC): C09J 3/16

ABSTRACTED-PUB-NO: JP49097052A

BASIC-ABSTRACT:

Adhesive compns. useful for bonding steel sheets, are prepd. by mixing a modified urethane resin with an epoxy resin and a curing agent. In an example, a mixt. of 230 g Epikote 828 (I) and 60 g xylylene diisocyanate was heated to 80 degrees, mixed dropwise with 137 g poly(oxytetramethylene)glycol, heated 2 hr at 90 degrees, mixed at 40 degrees with 24 g glycidol and 0.3 ml dibutyltin dilaurate, and heated to 60 degrees until the isocyanate group disappeared to give Epikote 828-glycidol-poly(oxytetramethylene)glycol-xylylene diisocyanate copolymer which (20 parts) was mixed with 80 parts I and 42 parts of a mixt. of dicyanamide 6, imidazole 1, an Al powder 30, and silica 5 parts to give an adhesive compn. The adhesive compn. was coated on surface-treated steel sheets and they bonded and cured 60 min. at 150 degrees. The bonding strength was 320 kg/cm<sup>2</sup> at -20 degrees and 226 kg/cm<sup>2</sup> at +80 degrees.

TITLE-TERMS: STEEL BOND CONTAIN POLYURETHANE EPOXY BLEND ADHESIVE

DERWENT-CLASS: A21 A25 A81 G03

CPI-CODES: A05-A01E1; A05-G01E1; A07-A03; A08-D01; A12-A05; G03-B02E;

Multipunch Codes: 012 028 038 04- 040 150 157 163 199 203 209 212 220 221 226 231 240 250 262 273 292 336 341 344  
346 359 37& 37- 400 47& 473 477 597 600 609 689 692 720 721 724 726

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L7: Entry 59 of 107

File: DWPI

May 10, 1996

DERWENT-ACC-NO: 1997-064057  
DERWENT-WEEK: 199706  
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TITLE: Electroconductive adhesive compsn. - contains epoxy resin, hardener, oligo-ether-urethane-di-epoxide,  
2,3-epoxy-tetra hydro-di-cyclo- penta:dienyl-capronate, alpha,beta-di-allyl ether of glycerine, and powdered silver(0)

INVENTOR: ERYGINA, V S; THAEVA, L A ; VOROBIEV, G A

PATENT-ASSIGNEE:

ASSIGNEE

ERYGINA V S

CODE

ERYGI

PRIORITY-DATA: 1988SU-4394019 (March 21, 1988)

PATENT-FAMILY:

PUB-NO

SU 1628508 A1

PUB-DATE

May 10, 1996

LANGUAGE

PAGES

005

MAIN-IPC

C09J009/02

APPLICATION-DATA:

PUB-NO

SU 1628508A1

APPL-DATE

March 21, 1988

APPL-NO

1988SU-4394019

DESCRIPTOR

INT-CL (IPC): C09 J 9/02; C09 J 163/02; C09 J 163/02; C09 J 175 04

ABSTRACTED-PUB-NO: SU 1628508A

BASIC-ABSTRACT:

The compsn. contains in pts.wt.: epoxy bisphenol A resin with optical density not less than 0.8 30-50; specified hardener 18.0-24.4; oligo-ether -urethane-di:epoxide 90-110; 2,3-epoxy:tetrahydro- dicyclopentadienyl-capr onate 30-60, alpha,beta-diallyl ether of glycerine 10-17; and fine-dispers ion powdered silver 700-800. The hardener is 33.3% soln. of amino:alkylimi dazoline in polyethylene-polyamine. Plasticiser is alpha,beta-diallyl ether of glycerine, and modifier is oligo-ether-urethane-di-epoxide. The components are combined by mixing according to standard technology. Tests show that the compsn. (examples 1-3) has viscosity (number of circle) 6.5-7.0, lifetime 3-4.5 unit, hardening mode 80/10 deg C, limit of shear strength 2.9-3.5 MPa, electrical vol. resistivity (1-3) x 10-4 omega.cm, and bending elasticity of film 1 cm.

USE - In electroconducting adhesive compsns. which can be used for assembly of sensitive elements of semiconductor devices and large integral circuits.

ADVANTAGE - Reduced hardening temp. to 80 deg.C and increased strength of adhesive joint up to 3.5 MPa with retained high electrical conductivity and elasticity.

CHOSEN-DRAWING: Dwg.0/0

TITLE-TERMS: ELECTROCONDUCTING ADHESIVE COMPOSITION CONTAIN POLY:EPoxide RESIN HARDEN

WEST

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JP 50-35232

L7: Entry 104 of 107

File: DWPI

Apr 3, 1975

DERWENT-ACC-NO: 1975-83696W  
DERWENT-WEEK: 197551  
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TITLE: Urethane-modified epoxy resin adhesive - for metal-metal bonding

PATENT-ASSIGNEE:

ASSIGNEE

SEKISUI CHEMICAL KK

CODE

SEKI

PRIORITY-DATA: 1973JP-0079131 (July 12, 1973)

PATENT-FAMILY

PUB-NO

JP 50035232 A

PUB-DATE

April 3, 1975

LANGUAGE

PAGES

000

MAIN-IPC

ABSTRACTED-PUB-NO: JP50035232A

BASIC-ABSTRACT:

Adhesive compsns., useful for bonding metal to metal, are prepd. from a mixt. of a hardener and a resin compsn. comprising 50-95% of epoxy resin and 5-50% of urethane-modified epoxy resin. Thus, a mixt. of 270 g Epikote-828 (I) and 17.4 g tolylene diisocyanate was mixed dropwise at 90 degrees C with 43 g polyoxytetramethylene glycol to give a urethane prepolymer, which reacts with epoxy resin at 100 degrees C to give a urethane-modified epoxy resin (II). A resin compsn. of 30 pts (II) and 70 pts (I) was mixed with dicayandiami de 6, imisazole 1, and Al powder 30, and silica 5 parts to give an adhesive compsn. which bonded steel sheets to give a laminate with peel strength 20 kg/25 mm. < p>TITLE-TERMS: URETHANE MODIFIED EPOXY RESIN ADHESIVE METAL METAL BOND

DERWENT-CLASS: A21 A81 G03

CPI-CODES: A05-A01E1; A05-G01E; A08-D01; A10-E01; A12-A05C; G03-B02E;

Multipunch Codes: 012 028 04- 040 150 199 203 209 220 221 226 231 240 250 273 333 336 341 344 346 359 400 44& 446  
47& 477 48- 597 600 609 692 720 721 725